



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-01-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL36DN6F7	CSES*OD6ATC2	A	3068	2018-01-12
Amount	UoM	Unit type	ST ECOPACK Grade	
76.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	6-5-1	12	pin	
Comment	PowerFLAT 5x6 double island			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	92
Lead	0.90	Soft solder	11855

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CSES*OD6ATC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.285	mg	supplier	die	Silicon (Si)	7440-21-3		0.245	mg	859649	3224
				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	56140	211
				supplier	metallization	Silver (Ag)	7440-22-4		0.002	mg	7018	26
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	7018	26
				supplier	metallization	Tungsten (W)	7440-33-7		0.004	mg	14034	53
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	7018	26
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	14035	53
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	3509	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	24561	92
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.002	mg	7018	26
				supplier	alloy	Copper (Cu)	7440-50-8		41.678	mg	870813	548395
				supplier	alloy	Iron (Fe)	7439-89-6		0.980	mg	20476	12895
Leadframe	Copper & its alloys	47.861	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.059	mg	1233	776
				supplier	alloy	Zinc (Zn)	7440-66-6		0.051	mg	1066	671
				supplier	metallization	Silver (Ag)	7440-22-4		5.093	mg	106412	67013
				supplier	alloy	Copper (Cu)	7440-50-8		41.678	mg	870813	548395
Soft solder	Solder	0.944	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	0.901	mg	954449	11855
				supplier	solder	Silver (Ag)	7440-22-4		0.024	mg	25424	316
				supplier	solder	Tin (Sn)	7440-31-5		0.019	mg	20127	250
Bonding wires	Other inorganic materials	0.217	mg	supplier	wire	Copper (Cu)	7440-50-8		0.217	mg	1000000	2855
Encapsulation	Other Organic Materials	26.534	mg	supplier	mold compound	Silica, vitreous	60676-86-0		24.571	mg	926019	323303
				supplier	mold compound	epoxy resin	85954-11-6		1.061	mg	39986	13961
				supplier	mold compound	phenol resin	26834-02-6		0.796	mg	29999	10474
				supplier	mold compound	carbon black	1333-86-4		0.106	mg	3996	1395